Press Release

YINCAE’S New High Purity Liquid Encapsulant: SMT 158HA

(Albany, NY) 10/20/2017 – YINCAE Advanced Materials has recently developed a unique amine based high purity liquid epoxy encapsulant: SMT 158HA. SMT 158HA is a slow cure underfill particularly designed for large components with small bumps and for applications with strict environmental regulations.

SMT 158HA has been particularly designed to be used for large component applications as it is highly viscous and allows air to easily escape from the gap during the underfilling process. The slow cure process allows air bubbles to migrate to the edge and escape. Though these processes generally do not significantly impact most components, they require more time to complete for large chips, and the design of SMT 158HA creates the conditions to lead to a void free underfill. As a result, components will exhibit lower thermal stress, and thus improved reliability for devices.

In addition to numerous processing benefits, SMT 158HA also offers many material benefits. SMT 158HA has a low CTE (20 ppm/K), a high glass transition temperature (156°C), is fast flowing, and offers a high adhesion strength.

For more information on YINCAE’s SMT 158HA underfill, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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